

OIF



OIF Workshop 448Gbps Signaling for AI Addressing the Next Rate Challenges

April 15-16, 2025

Nathan Tracy, OIF President

Sr. Principal Engineer, TE Connectivity

OIF - Where the optical networking industry's interoperability work gets done

Who:

- 150+ member companies
 - Network operators
 - System vendors
 - Component vendors
 - Test & measurement vendors
 - Academia & research

What:

- Identify needs, gaps
- Develop interoperable optical, electrical, and control solutions
- Publish Implementation Agreements

Why:

- Accelerate adoption of advanced technology to connect a global, open networked world

Challenge: Support innovation while preserving interoperability, optimizing performance and cost

150+ Member Companies

Identifies Industry Needs and Gaps

Publishes Implementation Agreements (specifications), Requirements and White Papers

Performs Interoperability Demonstrations

OPTICAL

Multi-Vendor Interoperability in Client Form Factors

1600ZR+

- <1000km Multi-Span Coherent DWDM

1600ZR, 800ZR, 400ZR

- >80km Coherent DWDM

1600LR, 800LR

- <10km Coherent Point-to-Point

ENERGY EFFICIENT INTERFACES

Next Generation Low Latency Interfaces for AI/ML & Data Centers

- Compute Optics Interface (COI)
- RTLR (Retimed Tx, Linear Rx)
- External Laser Sources (ELSFP)
- Co-Packaged Modules (3.2T)
- CEI-Linear

PROTOCOL

FlexE

- More Efficient
- Agile Networking

MANAGEMENT

Common Management Interface Specification (CMIS)

- Single Solution Ranging From Copper to Coherent
- Simplified Bring up Between Host and Module
- Supports Standard and Custom Interfaces

ELECTRICAL

Common Electrical I/O (CEI)

- High-Speed Building Blocks
- 448G, 224G, 112G, 56G, 28G
- LR, MR, VSR, XSR+, XSR, MCM, Linear
- Protocol Agnostic Link Training

NETWORKING

Transport SDN APIs

- Automation, Programmability

Enhanced Network Operations

- Artificial Intelligence
- Digital Twin
- DC Storage and Optical Multi-Layer Coordination

OIF • Member Driven Global Organization
 • 25+ Years of Service
 • 150+ Member Companies
 • 80+ IAs (specifications)
 • 65+ Interop Demos

OIF Removes Roadblocks

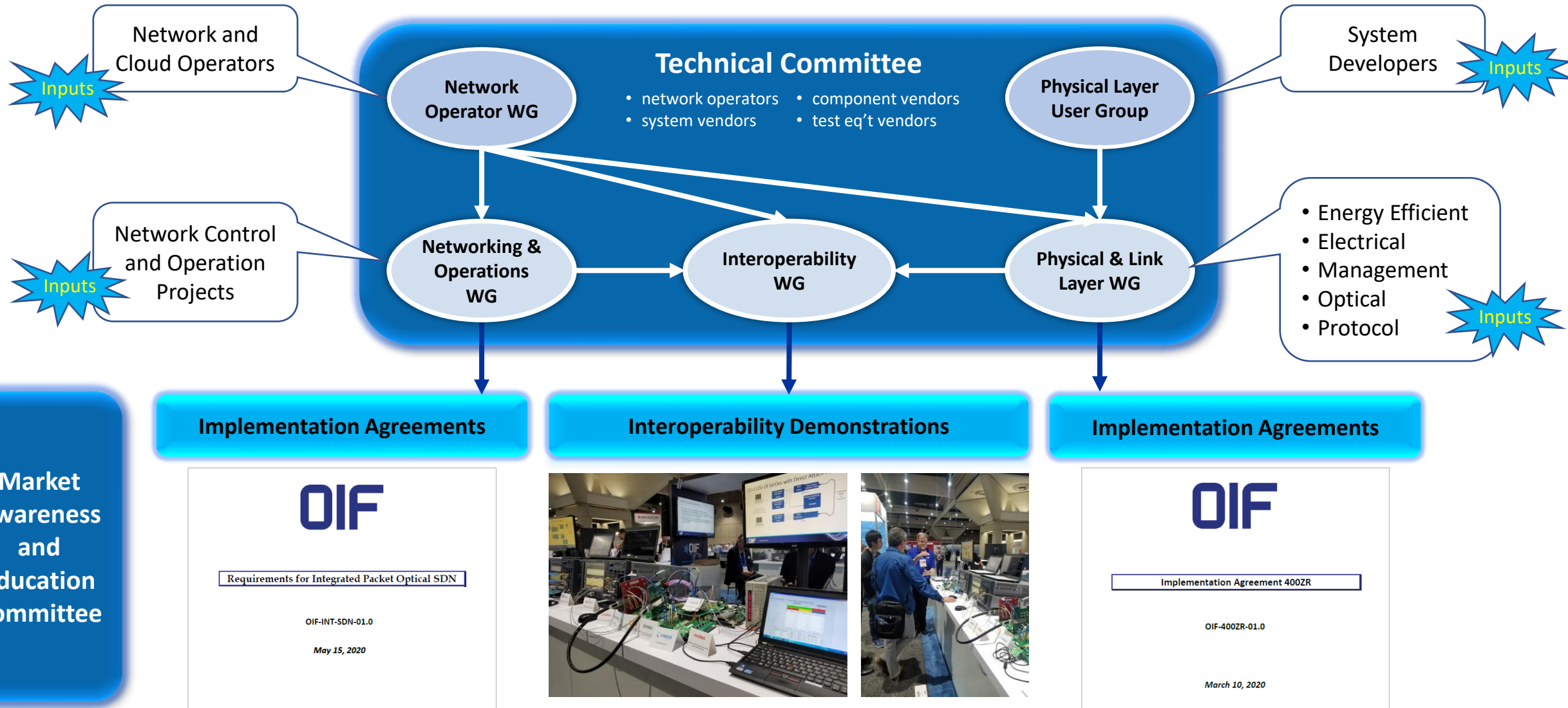
- Proprietary solutions
- Lacking or lagging standards
- Lack of opportunities for collaboration



- Building industry consensus
- Contributing to formal standard bodies
- Accelerating progress through collaboration

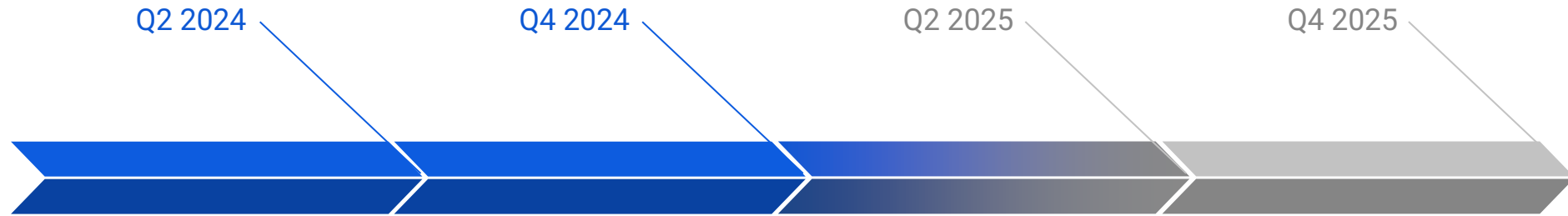


OIF: How Work Gets Done



How Did We Get To This Workshop?

A Conversation Started Around AI Needs



Initial Effort

OCP 1Q: Open Systems for AI: Vision White paper
OCP Short Reach Optical Interconnect

First Meetings

OIF: 448G Framework
EA TEF 4Q 2024: Initial Discussions

Exploration

SNIA 1Q: 400G AI Workshop
IEEE802.3: Ethernet for AI
OIF 2Q: 400G Workshop
OCP 2Q: Open Systems for AI Workshops

Gaining Clarity

4Q OCP Global Summit
...TBD

AGENDA

Day One



8:00 AM

Continental Breakfast in the Hotel Lobby

9:00 AM

Opening Remarks in the Sierra Ballroom - Nathan Tracy, OIF President, TE Connectivity

9:15 AM

SDO Panel - moderated by Nathan Tracy, OIF President, TE Connectivity

Kurtis Bowman, Ultra Accelerator Link Consortium

Anthony Constantine, SNIA

John D'Ambrosia, Futurewei, Chair, IEEE 802.3 NEA "Ethernet for AI" Assessment

Mark Nowell, Ultra Ethernet Consortium

Bijan Nowroozi, Open Compute Project

David Rodgers, Ethernet Alliance

Nathan Tracy, OIF

10:40 AM

Keynote - Tad Hofmeister, Google

11:20 AM

Coffee Break

11:40 AM

System Architecture Panel - moderated by Lisa Huff, Senior Principal Analyst, Optical Components, Omdia

Dave Ofelt, Juniper Networks

Mark Nowell, Cisco

Edo Poleg, Toga Networks (a Huawei company)

12:55 PM

Buffet Lunch

1:55 PM

Electrical Channel Panel - moderated by Alan Weckel, Founder and Technology Analyst, 650 Group

Mike Peng Li, Intel

Andrew Josephson, Samtec

John Calvin, Keysight Technologies

Vivek Shah, Molex

Srinivas Venkataraman, Meta Platforms

Howard Heck, TE Connectivity

4:05 PM

Coffee Break

4:35 PM

Keynote - Xu Wang, Meta Platforms

5:20 PM

SERDES Panel - moderated by Cathy Liu, OIF VP, Broadcom Inc.

Kaisheng (Klaus) Hu, Ciena

Mike Klempa, Alphawave Semi

Lenin Petra, Marvell

Kent Lusted, Synopsys

6:40 PM

Day One Closing Remarks

6:45 PM

Social Reception - Taco Truck & Drinks - Outdoors (weather permitting)

DAY TWO - WEDNESDAY APRIL 16



AGENDA Day Two

8:00 AM

Continental Breakfast in the Hotel Lobby

9:00 AM

Opening Remarks in the Sierra Ballroom

9:10 AM

Interconnect & Testing Panel - moderated by Tom Issenhuth, OIF MA&E Chair, Huawei Technologies

Matt Traverso, Marvell
Toshiyasu Ito, Yamaichi Electronics
Paul Brooks, VIAVI Solutions

10:10 AM

Keynote - Ashwin Gumaste, Microsoft

10:50 AM

Coffee Break

11:20 AM

Optical Modulation Panel - moderated by Scott Wilkinson, Lead Analyst, Networking Components, Cignal AI

Balazs Matuz, Huawei Technologies Co., Ltd.
Massimo Sorbara, Global Foundries

12:20 PM

Buffet Lunch

1:20 PM

Electrical Modulation Panel - moderated by Scott Wilkinson, Lead Analyst, Networking Components, Cignal AI

Naim Ben-Hamida, Ciena
Curtis Ling, MaxLinear
Peter Graumann, Microchip
David Stauffer, Kandou Bus
Adam Healey, Broadcom Inc.

2:55 PM

Coffee Break

3:25 PM

Keynote - Sara Zebian, OpenAI

4:00 PM

Q&A with Keynote Speakers - moderated by Nathan Tracy, OIF President, TE Connectivity

Ashwin Gumaste, Microsoft
Tad Hofmeister, Google
Xu Wang, Meta Platforms
Sara Zebian, OpenAI

4:35 PM

Closing Remarks

OIF

Thank You

